



PATENT
Attorney Docket No. 402715

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

KUMADA et al.

Application No. 10/623,772

Art Unit: 2812

Examiner: L. Schillinger

Filed: July 22, 2003

For: VIA-FILLING MATERIAL AND
PROCESS FOR FABRICATING
SEMICONDUCTOR INTEGRATED
CIRCUIT USING THE SAME

RESPONSE TO OFFICE ACTION

U.S. Patent and Trademark Office
220 20th Street S. Customer Window, Mail Stop Amendment
Crystal Plaza Two, Lobby, Room 1B03
Arlington, VA 22202

Dear Sir:

In response to the Office Action dated November 23, 2004, please enter the following amendments and consider the following remarks.

In re Appln. of KUMADA et al.
Application No. 10/623,772

TITLE AMENDMENTS

**VIA-FILLING MATERIAL AND PROCESS FOR FABRICATING
SEMICONDUCTOR INTEGRATED CIRCUIT USING THE SAME**